Product Change Notification: MAAN-05CKPE326

Date:

20-Oct-2026

Product Category:

Memory

Notification Subject:

CCB 8241 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for SST49LF008A-33-4C-NHE, SST49LF008A-33-4C-NHE-T, SST49LF080A-33-4C-NHE and SST49LF080A-33-4C-NHE-T available in 32L PLCC (11.5x14x3.37mm) package at MMT assembly site.

Affected CPNs:

MAAN-05CKPE326_Affected_CPN_10202026.pdf
MAAN-05CKPE326_Affected_CPN_10202026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for SST49LF008A-33-4C-NHE, SST49LF008A-33-4C-NHE-T, SST49LF080A-33-4C-NHE and SST49LF080A-33-4C-NHE-T available in 32L PLCC (11.5x14x3.37mm) package at MMT assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No

	Pre Change	Post Change	Change (Yes/No)
Wire Material	Au	Au CuPdAu	Yes
Die Attach Material	QMI519 (PFAS Free)	QMI519 (PFAS Free)	No
Molding Compound Material	G600V	G600V	No
Lead-Frame Material	A194	A194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as an additional bond wire material at MMT assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 17 November 2026 (date code: 2647)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2026					>	October 2026					November 2026				
Work Week	18	19	20	21	22		40	41	42	43	44	45	46	47	48	49
Initial PCN Issue Date		x														
Qual Report Availability										X						
Final PCN Issue Date										X						
Estimated Implementation Date														X		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 11, 2026: Issued initial notification.
October 20, 2026: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 17, 2026.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MAAN-05CKPE326_Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

SST49LF008A-33-4C-NHE

SST49LF008A-33-4C-NHE-T

SST49LF080A-33-4C-NHE

SST49LF080A-33-4C-NHE-T



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MAAN-05CKPE326

Date:

September 29, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for SST49LF008A-33-4C-NHE, SST49LF008A-33-4C-NHE-T, SST49LF080A-33-4C-NHE and SST49LF080A-33-4C-NHE-T available in 32L PLCC (11.5x14x3.37mm) package at MMT assembly site.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of palladium coated copper with gold flash (CuPdAu) as an additional bond wire material for SST49LF008A-33-4C-NHE, SST49LF008A-33-4C-NHE-T, SST49LF080A-33-4C-NHE and SST49LF080A-33-4C-NHE-T available in 32L PLCC (11.5x14x3.37mm) package at MMT assembly site.

QUAL ID:	R2600784
QUAL ID Rev.:	A
MP CODE:	U04071P3XF33
Part No.:	SST49LF080A-33-4C-NHE
Bonding No.:	BD-004372-01
CCB No.:	8241

Lead Frame

Paddle Size:	200 x 365 mils
Material:	A194
DAP Surface Prep:	Ag Ring
Process:	Etched
Lead Lock:	No
Part Number:	10103212
Lead Plating:	Matte tin
Treatment:	None

Bond Wire

Wire:	CuPdAu wire

Die Attach Material

Epoxy:	QMI519
Conductive:	Yes

Mold Compound

Mold Compound:	G600V

Package

Type:	PLCC
Pin/Ball Count:	32
Package Size:	11.5x14x3.37 mm

Manufacturing Information

Assembly Lot No.
MMT-271101030.000
MMT-271101557.000
MMT-271201547.000

Result: **Pass**

Qualification of U0407 mask / SST49LF080A-33-4C-NHE product / CuPdAu wire in 32L PLCC 11.5x14x3.37 mm package at MMT site is qualified for MSL3 at 245ºC as per JEDEC J-STD-020 standard and is passed in accordance to Specified JEDEC and Mil Standards.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Moisture Soak Precondition Prior to Stresses	**MSL3:** 150°C 24 hours Bake, 192 hours Moisture Soak at 30°C/60%RH, 3x Reflow at 245°C. Electrical Test Tester: NEXTEST_PV2 25°C and 80°C	JESD22-A113 , JEDEC J-STD-020	231 units each lot / 3 lots	0/231, 0/231, 0/231	Pass	
High Temp Storage	175°C / 504 hours. Electrical Test Tester: NEXTEST_PV2 25°C and 80°C	JESD22-A103	45 units / 3 lot	0/45, 0/45, 0/45	Pass	
Temperature Cycling	-65°C / +150°C Air to Air / 500 Cycles. Electrical Test Tester: NEXTEST_PV2 80°C	JESD22-A104	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
	WBP (Wire Bond Pull)		5 units lot 1	0/5, N/A, N/A	Pass	
Biased HAST	+130°C / 85%RH / 96 hours / Bias Voltage: 4.0V. Electrical Test Tester: NEXTEST_PV2 25°C and 80°C	JESD22-A110	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
Unbiased HAST	+130°C / 85%RH / 96 hours. Electrical Test Tester: NEXTEST_PV2 25°C	JESD22-A118	77 units each lot / 3 lots	0/77, 0/77, 0/77	Pass	
Physical Dimension (0Hr)	Within package diagram dimension	JESD22 B100 and B108	10 units each lot / 3 lots	0/30	Pass	
Wire Pull	Bond Strength Data Assembly	Mil. Std. 883-2011	5 units / 1 lot	0/5	Pass	
Bond Shear	Bond Strength Data Assembly	CDF-AEC-Q1 00-001	5 units / 1 lot	0/5	Pass	
Bond Line Thickness	0.60-1.50mils	SPI-45528	5 units each lot / 3 lots	0/15	Pass	
Wire sweep	15%	X-ray	15 wires each lot / 3 lots	0/45	Pass	